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U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

Docket No.: 43888-112

101833118

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Parties: 07/11/01  
Kenichiro SUETSUGU, Shunji HIBINO, Masato HIRANO,  
Atsushi YAMAGUCHI, and Mikiya NAKATA

2. Name and address of receiving party:  
Name: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

Address: 1006, Oaza-Kadoma  
Kadoma-Shi  
Osaka 571-8501, JAPAN

Additional names of conveying parties attached? ☐ Yes

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: June 4, 2001

Additional names & addresses attached? ☐ Yes

4. Application number or patent number:

If the document is being filed together with a new application, the execution date of the application is: June 4, 2001

A. Patent Application No.

B. Patent No.

Additional numbers attached? ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY  
Internal Address:

Street Address: 600 13<sup>th</sup> Street, N.W.

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00

- ☐ Enclosed  
☒ Authorized to be charged to deposit account

8. Deposit account number:  
500417

City: Washington State: DC Zip: 20005

07/16/2001 09:00:00 0000005 500417 09889167  
04 FC:581 40.00 CH

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Michael E. Fogarty, No. 36,139

July 11, 2001

Name and Registration No. of Person Signing

Signature

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

## **ASSIGNMENT**

WHEREAS, Kenichiro SUETSUGU, Shunji HIBINO, Masato HIRANO,  
Atsushi YAMAGUCHI and Mikiya NAKATA, hereinafter called the "Assignors," have jointly  
invented a new and useful invention entitled

Article having a circuit soldered with parts and method for recycling wastes of the same,  
for which they have:

- (a) filed an application for United States Letters Patent on  
\_\_\_\_\_ as (Serial No. \_\_\_\_\_ ); or
- (b) executed an application for United States Letters Patent on  
\_\_\_\_\_; or
- (c) filed a provisional application on \_\_\_\_\_  
as (Serial No. \_\_\_\_\_ ); and

WHEREAS, Matsushita Electric Industrial Co., Ltd., a corporation organized and  
existing under the laws of Japan, having a place of business at:  
1006, Oaza-Kadoma, Kadoma-shi, Osaka 571-8501 Japan,  
hereinafter called the "Assignee," is desirous of acquiring the entire right, title and  
interest in and to said invention, the application above identified, and in, to and under  
any Letters Patent which may be obtained to said invention, as hereinafter more fully  
set forth;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in  
consideration of the sum of One Dollar (\$1.00), and other valuable and legally sufficient  
considerations, the receipt of which by said Assignors from the said Assignee is hereby  
acknowledged, the said Assignors have sold, assigned and transferred, and by these presents  
do sell, assign and transfer unto the said Assignee, the entire, right, title and interest for the  
United States in and to the invention and application hereinabove identified, and any Letters  
Patent of the United States that may issue for said invention, together with the entire right, title  
and interest in and to said invention and applications for Letters Patent and Letters Patent  
therefor, in all countries foreign to the United States, including the full right to claim for any such  
application all benefits and priority rights under any applicable convention; to have and to hold for  
the sole and exclusive use and benefit of the said Assignee, its successors and assigns, to the  
full end of the term or terms for which any and all of said Letters Patent for said inventions may  
issue.

And the said Assignors do hereby covenant and agree, for themselves and their legal  
representatives, that they will assist the said Assignee in the prosecution of the application herein  
identified; in the making and prosecution of any other applications for Letters Patent that the said

Assignee may elect to make covering the invention herein identified, as hereinabove set forth; in vesting in the said Assignee like exclusive title in and to all such other applications and Letters Patent; and in the prosecution of any interference which may arise involving said invention, or any application or Letters Patent herein contemplated; and that they will execute and deliver to the said Assignee any and all additional papers which may be requested by the said Assignee to fully carry out the terms of this Assignment.

The undersigned hereby grant(s) the attorneys of McDermott, Will & Emery the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

And the Commissioner of Patents and Trademarks is hereby authorized and requested to issue Letters Patent to the said Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the said Assignors have hereunto set their hands and affixed their seal.

Date: June 4, 2001  
(Seal)

*Kenichiro Suetsugu*  
Kenichiro SUETSUGU

Date: June 4, 2001  
(Seal)

*Shunji Hibino*  
Shunji HIBINO

Date: June 4, 2001  
(Seal)

*Masato Hirano*  
Masato HIRANO

Date: June 4, 2001  
(Seal)

*Atsushi Yamaguchi*  
Atsushi YAMAGUCHI

Date: June 4, 2001  
(Seal)

*Mikiya Nakata*  
Mikiya NAKATA